

Micromax™ 5771

Electronic Inks and Pastes

Gold Conductor

Micromax™ 5771 is a cadmium-free*, screen printable, composition. It is used as a gold wire bondable conductor in high density hybrids. Micromax™ 5771 is capable of good automatic gold wire bonding yields with 1-mil and 2-mil wire. Micromax™ 5771 works well over multilayer dielectrics, such as Micromax™ QM44.

*Cadmium 'free' as used herein means that this is not intentionally added to the referenced product. Trace amounts however may be present.

Product information

Solvent or thinner	Micromax™ 8672
Solid content	83.7 - 85.7 %

Rheological properties

Viscosity	350 - 500 ^[1] Pa.s
[1]: Brookfield 2xHAT, SC4-14/6R, 10rpm, 25°C	

Application technique

Mask mesh	325 ^[2]
Mask emulsion	12 µm
Drying time	15 min
Drying temperature	150 °C
Theoretical coverage	50 - 80 cm ² /g
Recommended film thickness, fired	6 - 9 µm
Leveling time	10 - 15 min
[2]: Screen Types: Stainless steel	

Electrical properties

Surface resistivity	≤7 ^[3] mOhm per square
[3]: @10µm fired thickness	

Storage and stability

Shelf life	6 ^[4] months
[4]: in unopened containers, from date of shipment, at room temperature (<25°C)	

Additional information

How to use

Processing

• Substrates

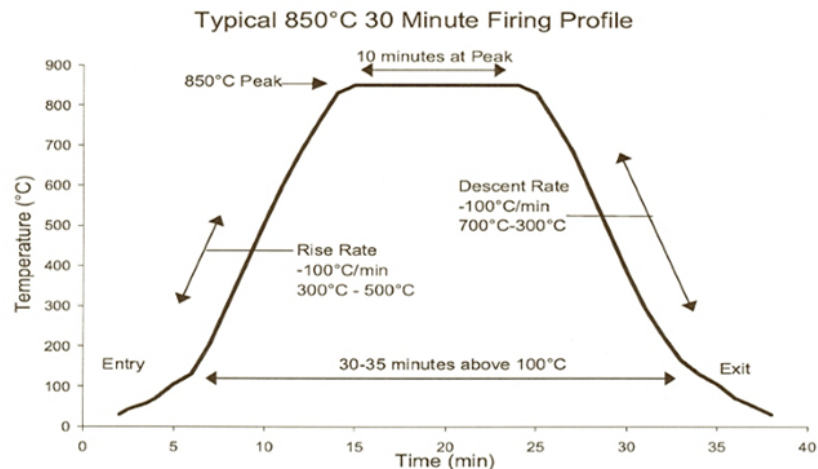
- Properties are based on tests using 96% alumina substrates. Substrates of other compositions and from various manufacturers

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may result in variations in performance properties.

- **Printing**
 - A 325 mesh stainless steel screen with an 12 μm (0.5 mil) emulsion thickness is recommended. Printing speeds up to 15 cm/s (6 in/s) can be achieved.
- **Drying**
 - Allow the wet print to level at room temperature, then dried.
- **Firing**
 - Dried prints should be fired in a belt furnace. Use a 30 minute cycle with a peak temperature of 850°C for 10 minutes. No significant changes in performance characteristics were seen after multiple refirings at 850°C. See Figure 1.
- **Bonding conditions**
 - Hughes 2460-III Automatic Gold Wire Bonder, stage 150°C, ceramic tool, 1.0 mil Au wire, tensile strength 8g min, elongation 3 to 5%. Hughes 2456-III Automatic Gold Wire Bonder, stage 150°C, ceramic tool, 2.0 mil Au wire, tensile strength 40-45g, elongation 3 to 5%. K&S Model 4123 Ultrasonic Wedge Bonder, tool #41471-2535-152, 1.0 mil Al wire (1% silicon).



Properties

- Information in this datasheet shows anticipated typical physical properties for Micromax™ 5771 based on specific controlled experiments in our labs and are not intended to represent the product specifications, details of which are available upon request.

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Storage and shelf life

Containers should be stored, tightly sealed, in a clean, stable environment at room temperature (<25 °C). Shelf life of material in unopened containers is six months from date of shipment. Some settling of solids may occur and compositions should be thoroughly mixed prior to use.

Safety and handling

For safety and handling information pertaining to this product, read Safety Data Sheet (SDS).

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.

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